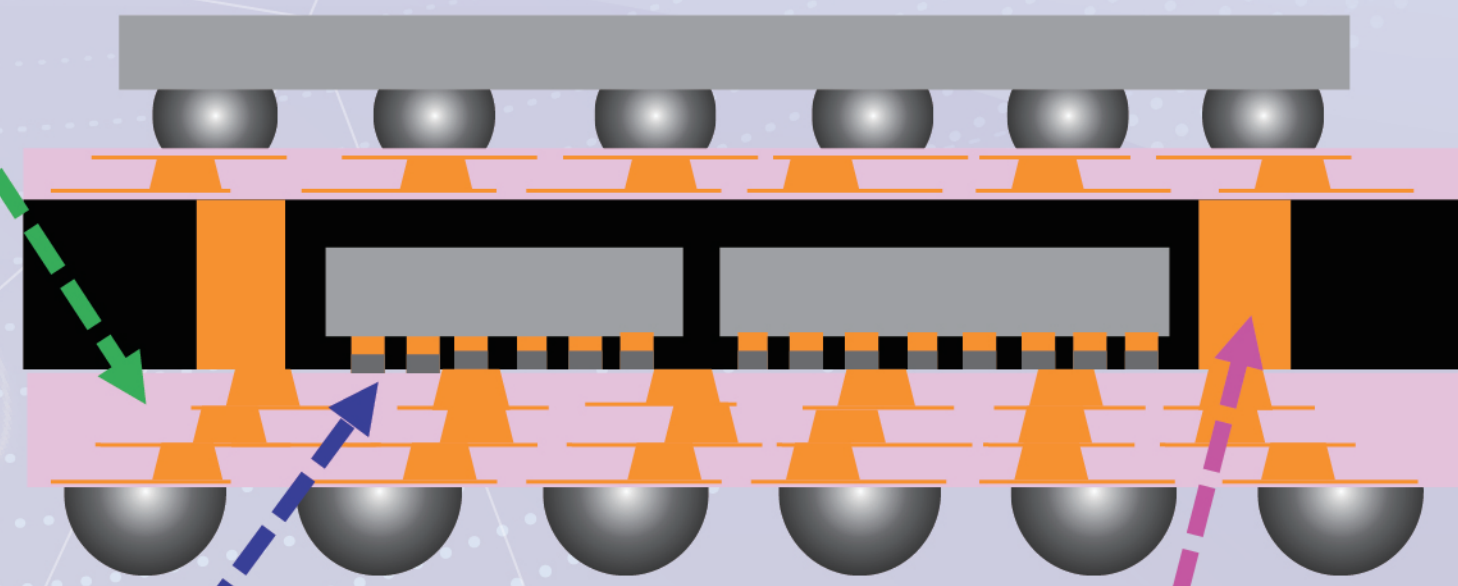


Thick Layer Photoresist For Plating

RDL / Fine RDL
FT : 5~15 μm
Plating : Cu



C4 / μ-Bump
FT : 20~100 μm
Plating : Cu / Ni / SnAg

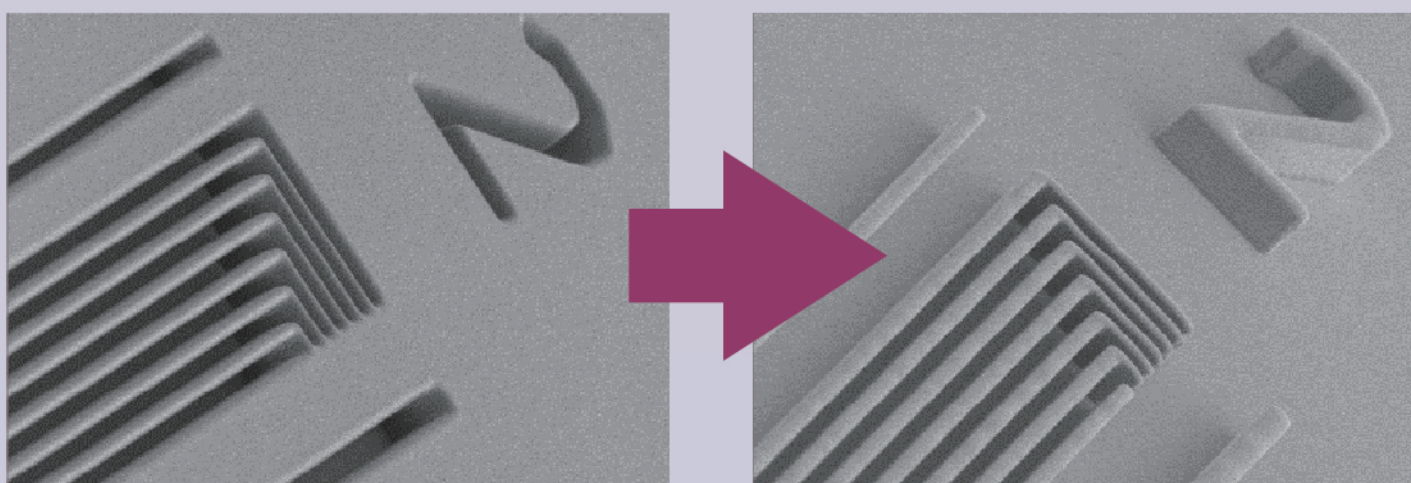
High Cu pillar
FT : >100 μm
Plating : Cu

Product Line up



Cu RDL

Negative Tone

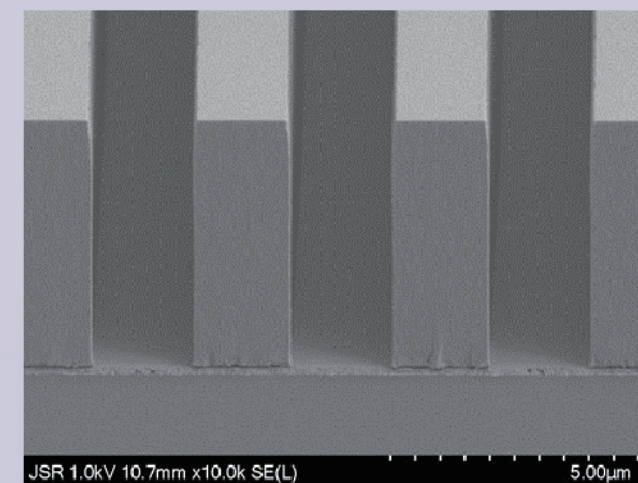


Cu Plate
THB stripped

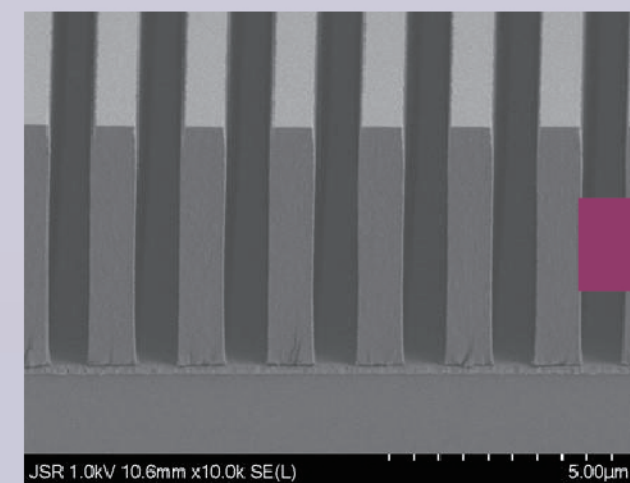
Cu Fine RDL

Positive Tone

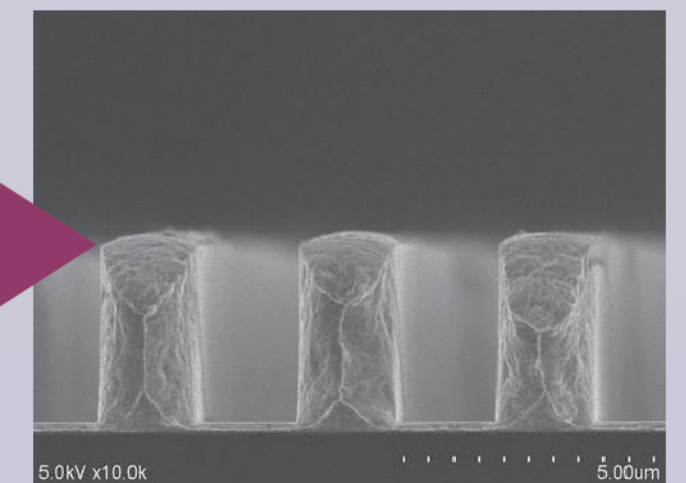
2.0 μm L/S



0.9 μm L/S

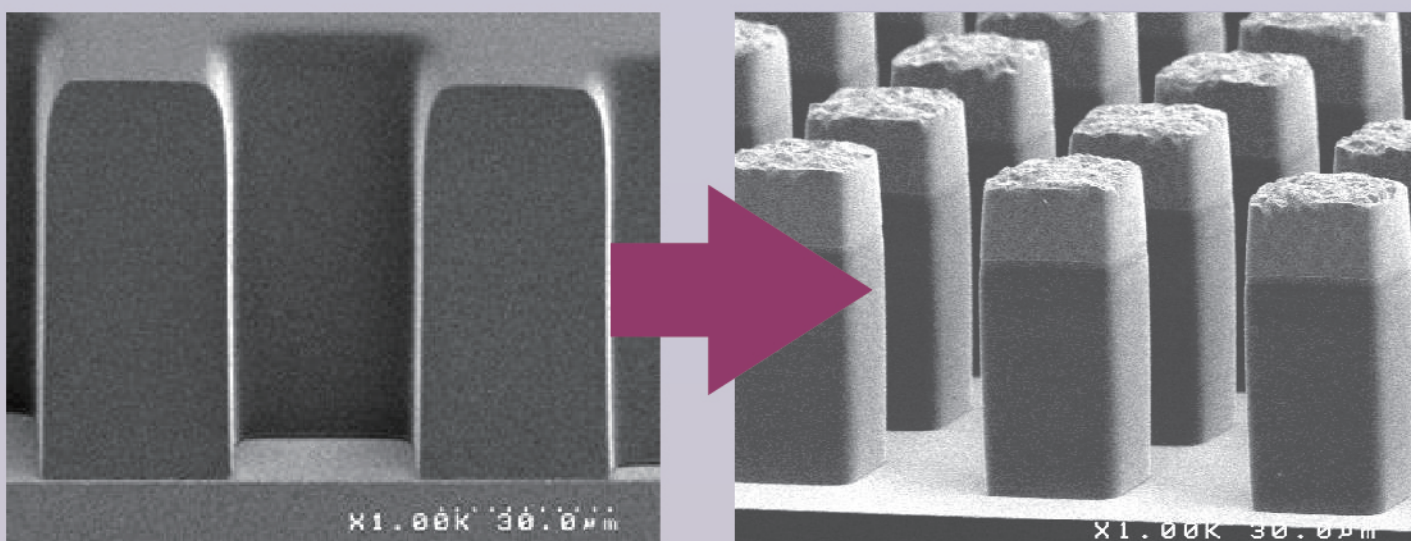


Film Thickness : 5 μm



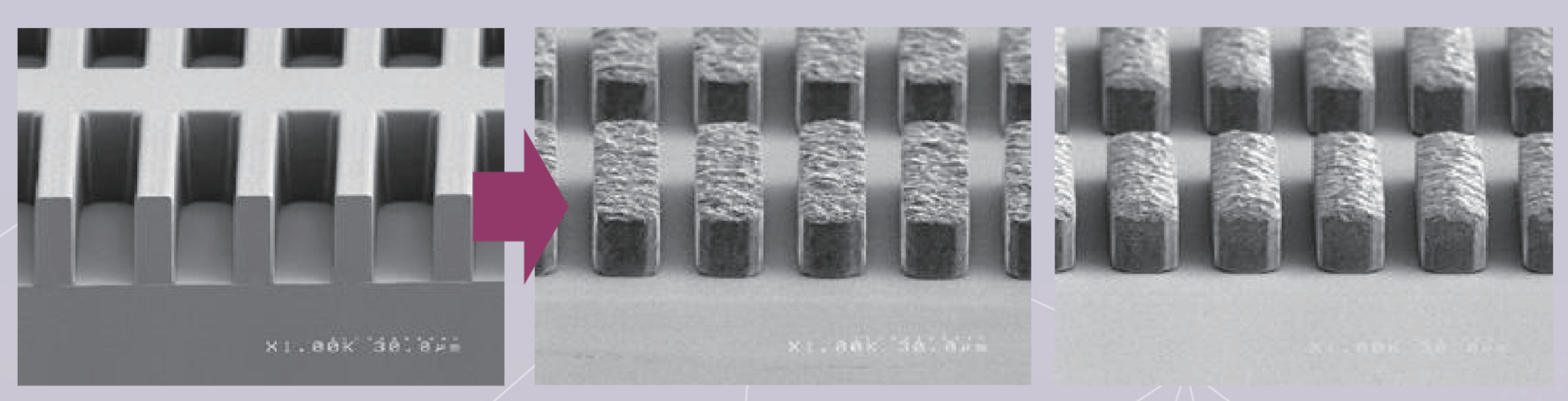
Cu Plate
THB stripped

Cu / Ni / Solder Bump



Cu / Ni / SnAg Plate
THB stripped

Au Bump

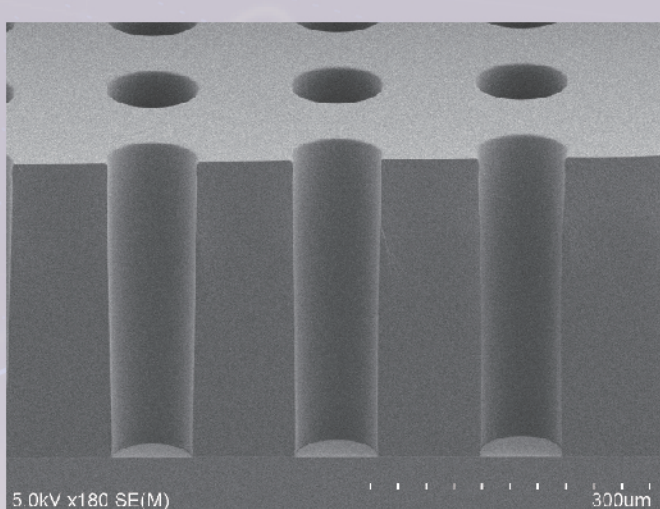


Cyanide Au Plate
THB stripped

Non-cyanide Au Plate
THB stripped

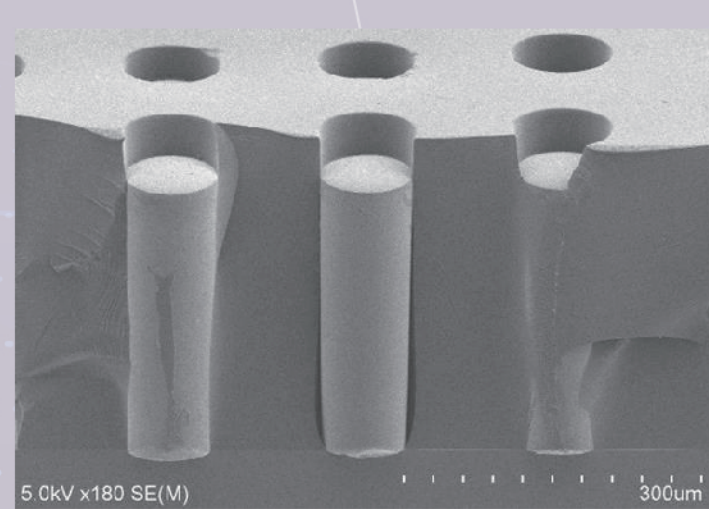
High Cu Pillar

After Development



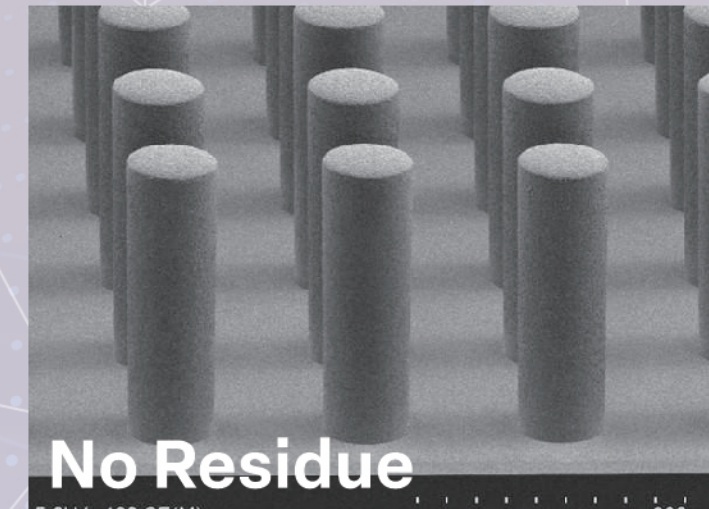
Film Thickness
340 μm / 100 μm φ

After Cu Plating



Cu Height 290 μm
w/ Cu Plating Chemical
from Ishihara Chemical

After Stripping



No Residue

